

Connector for microSD™ Card (Push-push Type)

SCHA Series



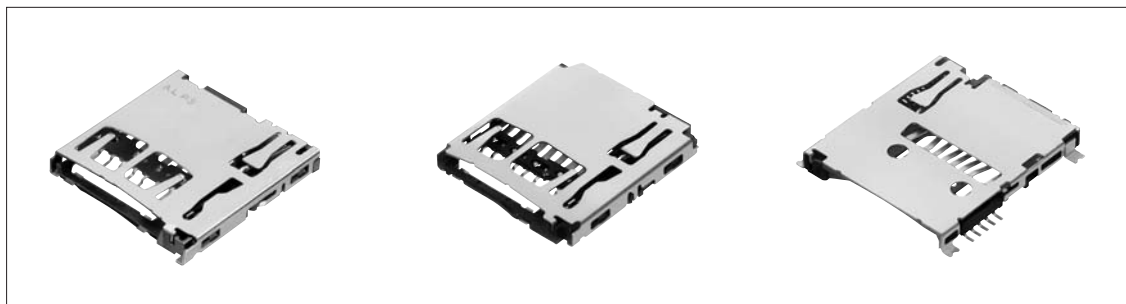
Compact low-profile type most suitable for mobile phones.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM



For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module

Features

- Improved operability from a clear click feel.
- Good operational feel.

Applications

- For mobile phones, personal digital assistants, digital still cameras, compact audio equipment.

Typical Specifications

| Items | | Specifications | |
|-----------------------------|---------------------------------|------------------------------|------------|
| Structure | Applicable media | microSD™ Card | |
| | Mounting type | Surface mounting type | |
| | Mounting style | Standard mount/Reverse mount | |
| | Media ejection structure | Push-push type | |
| Performance | Operating temperature range | -20°C to +70°C | |
| | Voltage proof | 500V AC 1minute | |
| | Insulation resistance (Initial) | 1,000MΩ min. | |
| | Contact resistance (Initial) | Connector contacts | 100mΩ max. |
| | | Detection switch | 500mΩ max. |
| Insertion and removal cycle | 5,000cycles | | |

Product Line

| Media ejection structure | Mounting system | Features | Stand-off (mm) | Packing system | Product No. | Drawing No. |
|--------------------------|-----------------|----------------|----------------|----------------|-------------|-------------|
| Push-push type | Standard mount | Without switch | 0 | Taping | SCHA1A0101 | 1 |
| | | With switch | | | SCHA1B0100 | 2 |
| | Reverse mount | SCHA2B0300 | | | 3 | |

Dimensions
Standard mount

Unit:mm

| No. | Style | PC board mounting hole dimensions (Viewed from the mounting face side) |
|-----|------------------------------|--|
| 1 | <p>Without switch</p> | <p> No parts area Land area No pattern area </p> |
| 2 | <p>With switch</p> | <p> Land area No pattern area No parts area </p> |

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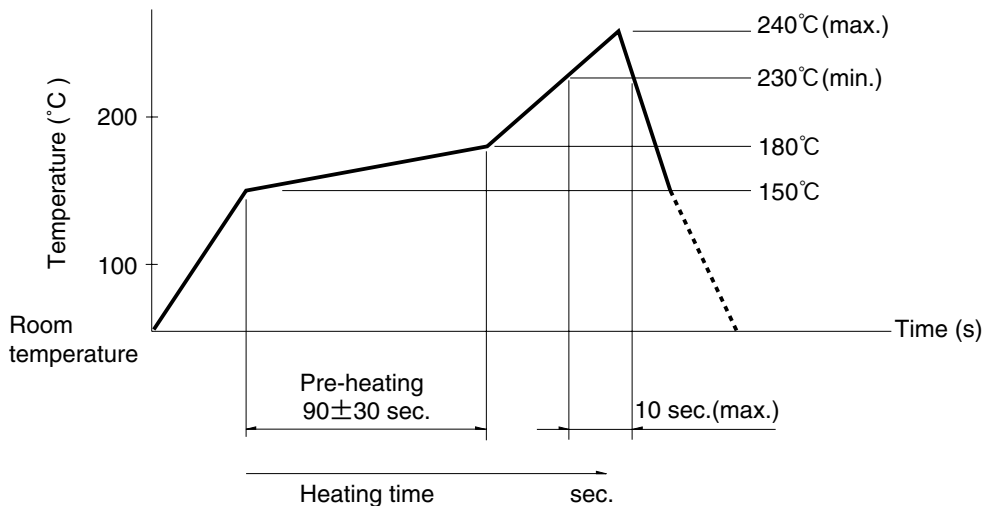
For Express Card™

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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



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Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.